

# SERIES 2000 HIGH PERFORMANCE REMOTE ANTENNA RFM AND TUNING MODULE

## FEATURES

- Best in Class Performance Through Patented HDX Technology
- High Power Output
- Extended Antenna Induction Range
- Reader Antenna Distance Up to 120 Meters
- Proven In Harsh Industrial Environments
- Easy To Install And Use

## APPLICATIONS

- Access Control
- Vehicle Identification
- Container Tracking
- Asset Management
- Waste Management



## DESCRIPTION

The Texas Instruments' low-frequency (LF) reader provides all the functionality required to communicate with Texas Instruments 134.2 kHz LF transponders which are available in a variety of form factors. The RI-RFM-008B radio frequency power module is capable driving the RI-ACC-008B, which then forms the resonant circuit with the antenna. The distance between the antenna - RI-ACC-008B combination and the reader (RI-RFM-008B + control module) can be extended up to 120 meters when connected by a symmetrical twinax cable.

The RI-ACC-008B radio frequency power module is capable driving a variety of antennas with extended inductance ranges from 8µH to 80µH including TI standard antennas RI-ANT-G01E, RI-ANT-G02E, RI-ANT-G04E gate antennas as well as RI-ANT-S01C and RI-ANT-S02C stick antennas. The RI-RFM-008 is designed to be connected to control modules RI-CTL-MB2A (RS232 interface) or RI-CTL-MB6A (RS422/485 interface) which provide the interface to connect a host system, power supply connectors and additional I/O's. The RI-RFM-008B module in combination with a control module and the RI-ACC-008B is well suited for usage in a broad range of applications including, but not limited to, access control, vehicle identification, container tracking, asset management and waste management applications.

The Series 2000 High Performance Remote Antenna RFM together with the Antenna Tuning Module supports the use of antennas installed at a distance of up to 120 meters. It is the interface between the 134.2 kHz HDX/FSK transponder and the Data Processing Unit. It sends an energizing signal to the transponder, modulates the RF signal to send data to the transponder, receives the identification signal and processes it for digital decoding.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

## RI-RFM-008B, RI-ACC-008B

SCBS850-MARCH 2001

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

	RI-RFM-008B	RI-ACC-008B	UNIT
Operating Temperature	-25 to +70	-25 to +70	°C
Storage Temperature	-40 to +85	-40 to +85	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## **RECOMMENDED OPERATING CONDITIONS**

over operating free-air temperature range (unless otherwise noted)

	RI-RFM-008B	RI-ACC-008B
Power Supply	7 to 24 Vdc, regulated	—

#### **OPERATING CHARACTERISTICS**

over operating free-air temperature range (unless otherwise noted)

PARAMETER	PART NUMBER					
PARAMETER	RI-RFM-008B	RI-ACC-008B	UNIT			
Relative Humidity	< 97% non-condensing, IEC 68-2-3	< 97% non-condensing, IEC 68-2-30 Test Db, 21 cycles				
RF Transmit Frequency	134.2	134.2				
Transponder Types	134.2 kHz HDX/FSK	134.2 kHz HDX/FSK				
Antenna Tuning Range	Determined by the tuning-board	8 to 80 μH				
Antenna Resonance Voltage	Max. 280 / 400 Vpeak Max. 380 Vpeak (depending on the configured inductance range)					
Dimensions (L $\times$ W $\times$ H)	$(83 \times 93 \times 44) \pm 1$ $(115 \times 70 \times 27) \pm 1$		mm			
Weight	160 162		g			
Cable (RFM to tuning-board)	Symmetrical shielded cable (twin-a					



www.ti.com

#### PACKAGING INFORMATION

STRUMENTS

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
RI-ACC-008B-00	OBSOLETE			1		TBD	Call TI	Call TI
RI-ACC-008B-30	ACTIVE			0	1	TBD	Call TI	Call TI
RI-RFM-008B-30	ACTIVE			0	1	TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DLP® Products	www.dlp.com	Broadband	www.ti.com/broadband
DSP	dsp.ti.com	Digital Control	www.ti.com/digitalcontrol
Clocks and Timers	www.ti.com/clocks	Medical	www.ti.com/medical
Interface	interface.ti.com	Military	www.ti.com/military
Logic	logic.ti.com	Optical Networking	www.ti.com/opticalnetwork
Power Mgmt	power.ti.com	Security	www.ti.com/security
Microcontrollers	microcontroller.ti.com	Telephony	www.ti.com/telephony
RFID	www.ti-rfid.com	Video & Imaging	www.ti.com/video
RF/IF and ZigBee® Solutions	www.ti.com/lprf	Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2009, Texas Instruments Incorporated